

S.NO	Facility Name	Company/model	Usage	Cost [INR]	Cost per hour or sample or Process	Remark
01	E-Beam Evaporation	Excel Instruments	Deposition of Metal and Oxide materials	400	Slot	400 INR upto 70nm 800 INR from 70-150 nm
02	Thermal Evaporation	Excel Instruments	Deposition of Metal and Oxide materials	300	Slot	300 INR upto 70nm 600 INR from 70-150 nm
03	RF - Sputtering	Excel Instruments	Deposition of Metal and Oxide materials	500	Slot	500 rps upto 70nm 1000 INR from 70-150 nm
04	Parameter Analyzer (4200A)	M/S Tektronix Asia Ltd Model: Keithley 4200A-SCS	Electrical Characterization	100	Hrs	Max. slot time 3 hrs
	Wafer Probe for Device Characterization	M/S Formfactor Inc Model: EPS 150 FA	Probe station for electrical characterization			
05	FESEM	M/S FEI Company of USA Model: APREO 2 S HiVac	Surface characterization and patterning	200	Sample	5 images per sample, Max. 2 hours/slot
06	E-Beam Lithography System	RAITH	Mask patterning	500	Sample	Max. slot time per sample 30 min
07	Direct Writing Maskless Lithography System	Durham Magneto Optics Ltd Model: MICRO WRITER ML3 PRO	Mask patterning	500	Sample	Max. slot time per sample 30 min
08	Double - Side Mask Aligner System	Optical Associates Inc Model: OAI 806 EBA 500W NUV	Mask patterning	400	Sample	Max. slot time per sample 30 min
09	Wafer Dicing Tool	Disco Corporation Japan Model: DAD323	Dicing wafers (2", 4")	1000	Wafer	
10	Stylus Based Profiler	Bruker Singapore Pvt. Ltd. Model: DEKTAK –XT	Thin film depth characterization	100	Sample	Max. slot time 30 min
11	Semi-Automatic Wire Bonder	HYBOND Model: HYBOND 626	Wire bonding (Ball bonding, Wedge bonding)	400-800	8 Bonds/Sample	400 INR/Al 800 INR/Au
12	Horizontal Three Stack (Oxygen Diffusion & Annealing) Furnace System	Company: SVCS Process Innovation	Dry/Wet oxidation, p/n type doping			
13	Vacuum Oven	M/K Scientific Instruments Model: MKSI- 10SC	Drying and Annealing	100	2 Hrs	Max. process time 12 Hrs
14	Spin Coater	NAVSON Model: NT12000V1	Photoresist coating, thin film development	50	Sample	Except Lithography chemicals
15	Chemical Benches	Nano-Clean	Wafer cleaning, chemical reactions, hydrothermal growth	100	Process	Max. slot time 2 hrs

